

# OL-NX5P2924C

wafer level chip-scale package, 6 bumps; 0.87 x 1.37 x 0.50 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP6
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	21-4-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.34	-	1.37	1.4	mm
E	package width	0.84	-	0.87	0.9	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.5	-	m
n <sub>2</sub>	actual quantity of termination	-	-	6	-	



2. Package outline

WLCSP6: wafer level chip-scale package, 6 bumps; 0.87 x 1.37 x 0.50 mm NX5P2924C

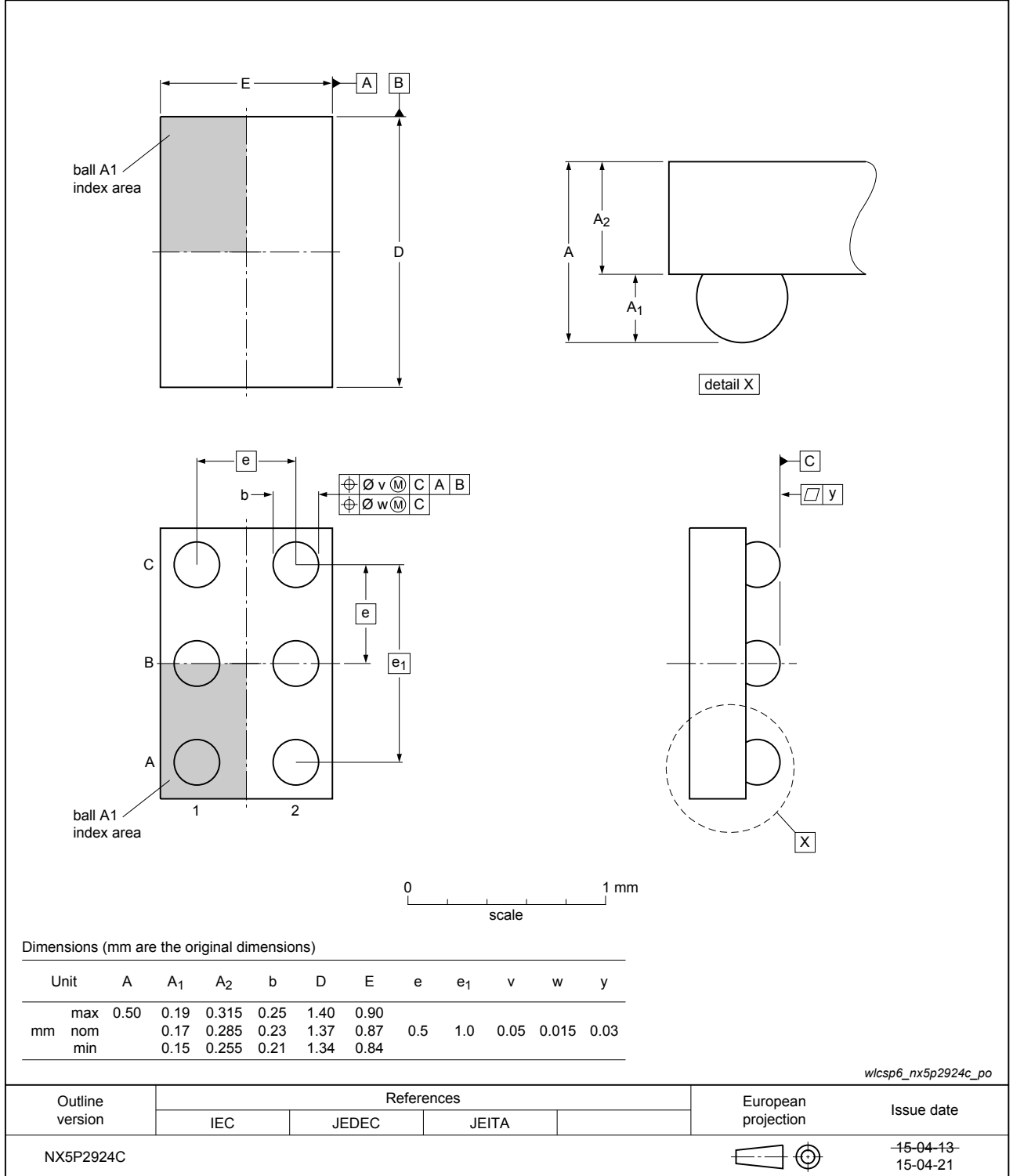


Fig. 1. Package outline WLCSP6 (OL-NX5P2924C)

### 3. Legal information

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